

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2918279

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
BYEONG YONG YOO	06/17/2014
SUNG BAE KIM	06/17/2014
IL GUK WOO	06/18/2014
YEONG TAE OH	06/18/2014
HEE SEUNG NA	06/17/2014
RECEIVING PARTY DATA	
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Postal Code:	100-180
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14369405
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NAME OF SUBMITTER:	MINCHEOL KIM
SIGNATURE:	/Mincheol Kim/
DATE SIGNED:	06/27/2014
Total Attachments: 2	
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ASSIGNMENT

WHEREAS, I, the undersigned, have invented certain new and useful improvements entitled "MODULE FOR TREATMENT OF CARBON DIOXIDE AND TREATMENT METHOD THEREOF" for which I have executed a Declaration for a U.S. Patent Application on the same date hereof or for which I filed U.S. Patent Application No. 14/369,405 on June 27, 2014. In case this document is signed after the filing date and is provided without the filing date and/or the application number, I authorize the registrants of Knobbe, Martens, Olson & Bear, LLP, Customer No. 20,995 to include the filing date and application number in the blanks before filing this document for recordation with the United States Patent and Trademark Office.

AND WHEREAS, DAEWOO SHIPBUILDING & MARINE ENGINEERING CO., LTD. (hereinafter "ASSIGNEE"), a Korean Corporation, with its principal place of business at 85, Da-dong, Jung-gu, Seoul, 100-180, Republic of Korea, desires to acquire the entire right, title, and interest in and to the said improvements and the said Application.

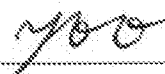
NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I do hereby acknowledge that I have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest, to and under the said improvements, and the said Application and all provisional applications relating thereto, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof; and I hereby authorize and request the Commissioner of Patents of the United States of America to issue all Letters Patent for said improvements to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I DO HEREBY sell, assign, transfer, and convey to ASSIGNEE, his successors, legal representatives, and assigns all claims for damages and all remedies arising out of any violation of the rights assigned hereby that may have accrued prior to the date of assignment to ASSIGNEE, or may accrue hereafter, including, but not limited to, the right to sue for, collect, and retain damages for past infringements of the said Letters Patent before or after issuance.

AND I HEREBY covenant and agree that I will communicate to the said ASSIGNEE, successors, legal representatives and assigns, any facts known to me respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

Name: YOO, Byeong Yong

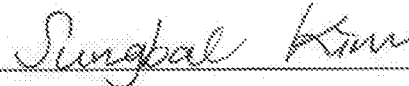
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